

WHAT IS CLAIMED IS:

1. A mounting structure of a semiconductor package for establishing electrical connection of a pad on a printing circuit board to a connection wiring by soldering the semiconductor package, comprising:

said pad being integrally formed with a via;

said soldering being performed by penetrating a part of solder within said via so that said connection wiring is connected to said pad through said via at a layer different from a layer of said pad.

2. A mounting structure of a semiconductor package as set forth in claim 1, wherein said via is depressed from said pad of annular shape on said printed circuit board to project for establishing electrical connection with the connection wiring at the tip end thereof.

3. A mounting structure of a semiconductor package as set forth in claim 1 or 2, wherein a plating is provided on the surface of said pad and an inner surface of said via.

4. A mounting structure of a semiconductor package as set forth in claim 1, wherein said via is formed in said pad of said printed circuit board corresponding to a corner of said semiconductor package.

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5. A mounting structure of a semiconductor package as set forth in claim 1 or 2, wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

6. A mounting structure of a semiconductor package as set forth in claim 3, wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

7. A mounting structure of a semiconductor package as set forth in claim 2, wherein a vacant space is certainly provided between an outer circumference of said pad and a solder resist on said printed circuit board.

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